ABSTRACT

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH PAD CONNECTION AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit packaging system includes: forming a lead having a lead bottom side and a lead top side; applying a passivation over the lead with the lead top side exposed from the passivation; forming an interconnect structure directly on the passivation and the lead top side, the interconnect structure having an inner pad and an outer pad with a recess above the lead top side; mounting an integrated circuit over the inner pad and the passivation; and molding an encapsulation over the integrated circuit.
(Fig. 1)